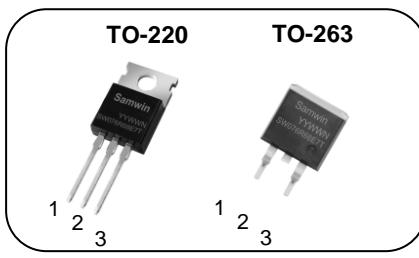
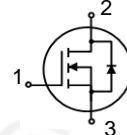


**N-channel Enhanced mode TO-220/TO-263 MOSFET****Features**

- High ruggedness
- Low  $R_{DS(ON)}$  (Typ 7.6mΩ)@ $V_{GS}=10V$
- Low Gate Charge (Typ 70nC)
- Improved dv/dt Capability
- 100% Avalanche Tested
- Application:Synchronous Rectification, Li Battery Protect Board, Inverter

**1. Gate 2.Drain 3.Source**

**$BV_{DSS}$  : 68V**  
 **$I_D$  : 85A**  
 **$R_{DS(ON)}$  : 7.6mΩ**

**General Description**

This power MOSFET is produced with advanced technology of SAMWIN. This technology enable the power MOSFET to have better characteristics, including fast switching time, low on resistance, low gate charge and especially excellent avalanche characteristics.

**Order Codes**

Item	Sales Type	Marking	Package	Packaging
1	SW P 076R68E7T	SW076R68E7T	TO-220	TUBE
2	SW B 076R68E7T	SW076R68E7T	TO-263	TUBE

**Absolute maximum ratings**

Symbol	Parameter	Value		Unit
		TO-220	TO-263	
$V_{DSS}$	Drain to source voltage	68		V
$I_D$	Continuous drain current (@ $T_C=25^\circ C$ )	85*		A
	Continuous drain current (@ $T_C=100^\circ C$ )	62*		A
$I_{DM}$	Drain current pulsed (note 1)	340		A
$V_{GS}$	Gate to source voltage	$\pm 20$		V
$E_{AS}$	Single pulsed avalanche energy (note 2)	180		mJ
$E_{AR}$	Repetitive avalanche energy (note 1)	18		mJ
dv/dt	Peak diode recovery dv/dt (note 3)	5		V/ns
$P_D$	Total power dissipation (@ $T_C=25^\circ C$ )	138.9		W
	Derating factor above 25°C	1.1		W/°C
$T_{STG}, T_J$	Operating junction temperature & storage temperature	-55 ~ + 150		°C
$T_L$	Maximum lead temperature for soldering purpose, 1/8 from case for 5 seconds.	300		°C

\*. Drain current is limited by junction temperature.

**Thermal characteristics**

Symbol	Parameter	Value		Unit
		TO-220	TO-263	
$R_{thjc}$	Thermal resistance, Junction to case	0.9		°C/W
$R_{thja}$	Thermal resistance, Junction to ambient	49		°C/W

### Electrical characteristic ( $T_J = 25^\circ\text{C}$ unless otherwise specified )

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
<b>Off characteristics</b>						
$\text{BV}_{\text{DSS}}$	Drain to source breakdown voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	68			V
$\Delta \text{BV}_{\text{DSS}} / \Delta T_J$	Breakdown voltage temperature coefficient	$I_D=250\mu\text{A}$ , referenced to $25^\circ\text{C}$		0.09		$^\circ\text{C}$
$I_{\text{DSS}}$	Drain to source leakage current	$V_{\text{DS}}=68\text{V}$ , $V_{\text{GS}}=0\text{V}$		1		$\mu\text{A}$
		$V_{\text{DS}}=54\text{V}$ , $T_J=125^\circ\text{C}$		50		$\mu\text{A}$
$I_{\text{GSS}}$	Gate to source leakage current, forward	$V_{\text{GS}}=20\text{V}$ , $V_{\text{DS}}=0\text{V}$		100		nA
	Gate to source leakage current, reverse	$V_{\text{GS}}=-20\text{V}$ , $V_{\text{DS}}=0\text{V}$		-100		nA
<b>On characteristics</b>						
$V_{\text{GS(TH)}}$	Gate threshold voltage	$V_{\text{DS}}=V_{\text{GS}}$ , $I_D=250\mu\text{A}$	2		4	V
$R_{\text{DS(ON)}}$	Drain to source on state resistance	$V_{\text{GS}}=10\text{V}$ , $I_D=40\text{A}$ , $T_J=25^\circ\text{C}$		7.6	8.8	$\text{m}\Omega$
		$V_{\text{GS}}=10\text{V}$ , $I_D=40\text{A}$ , $T_J=125^\circ\text{C}$		12.3		$\text{m}\Omega$
$G_{\text{fs}}$	Forward transconductance	$V_{\text{DS}}=5\text{V}$ , $I_D=40\text{A}$		50		S
<b>Dynamic characteristics</b>						
$C_{\text{iss}}$	Input capacitance	$V_{\text{GS}}=0\text{V}$ , $V_{\text{DS}}=34\text{V}$ , $f=1\text{MHz}$		3467		pF
$C_{\text{oss}}$	Output capacitance			222		
$C_{\text{rss}}$	Reverse transfer capacitance			200		
$t_{\text{d(on)}}$	Turn on delay time	$V_{\text{DS}}=34\text{V}$ , $I_D=30\text{A}$ , $R_G=4.7\Omega$ , $V_{\text{GS}}=10\text{V}$ (note 4,5)		22		ns
$t_r$	Rising time			58		
$t_{\text{d(off)}}$	Turn off delay time			56		
$t_f$	Fall time			25		
$Q_g$	Total gate charge			70		nC
$Q_{\text{gs}}$	Gate-source charge	$V_{\text{DS}}=54\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_D=30\text{A}$ , $I_G=3\text{mA}$ (note 4,5)		19		
$Q_{\text{gd}}$	Gate-drain charge			26		
$R_g$	Gate resistance	$V_{\text{DS}}=0\text{V}$ , Scan F mode		3.7		$\Omega$

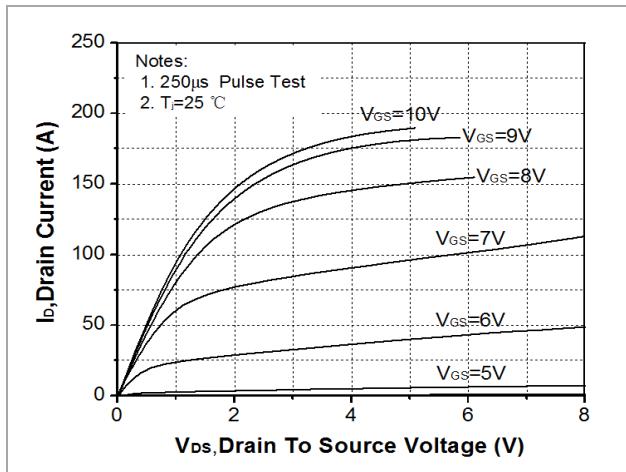
### Source to drain diode ratings characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous source current	Integral reverse p-n Junction diode in the MOSFET			85	A
$I_{\text{SM}}$	Pulsed source current				340	A
$V_{\text{SD}}$	Diode forward voltage drop.	$I_s=45\text{A}$ , $V_{\text{GS}}=0\text{V}$			1.4	V
$t_{\text{rr}}$	Reverse recovery time	$I_s=30\text{A}$ , $V_{\text{GS}}=0\text{V}$ , $dI_F/dt=100\text{A}/\mu\text{s}$		34		ns
$Q_{\text{rr}}$	Reverse recovery charge			45		nC

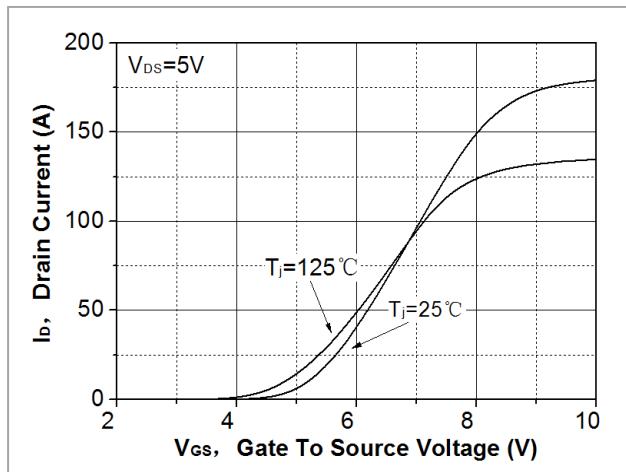
#### ※ Notes

- Repetitive rating : pulse width limited by junction temperature.
- $L = 0.5\text{mH}$ ,  $I_{\text{AS}} = 26.8\text{A}$ ,  $V_{\text{DD}} = 30\text{V}$ ,  $R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$
- $I_{\text{SP}} \leq 30\text{A}$ ,  $di/dt = 100\text{A}/\mu\text{s}$ ,  $V_{\text{DD}} \leq \text{BV}_{\text{DSS}}$ , Starting  $T_J = 25^\circ\text{C}$
- Pulse Test : Pulse Width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
- Essentially independent of operating temperature.

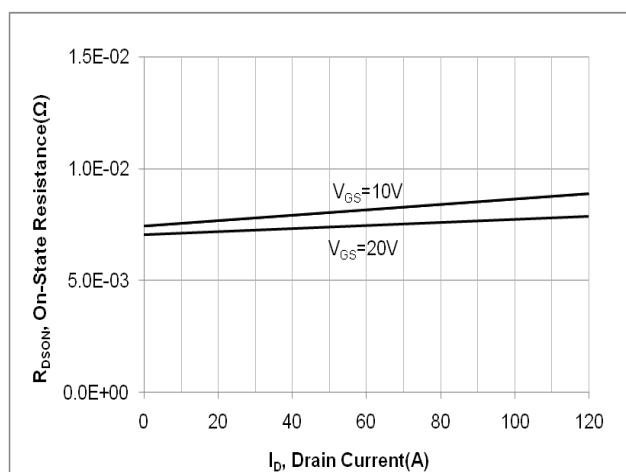
**Fig. 1. On-state characteristics**



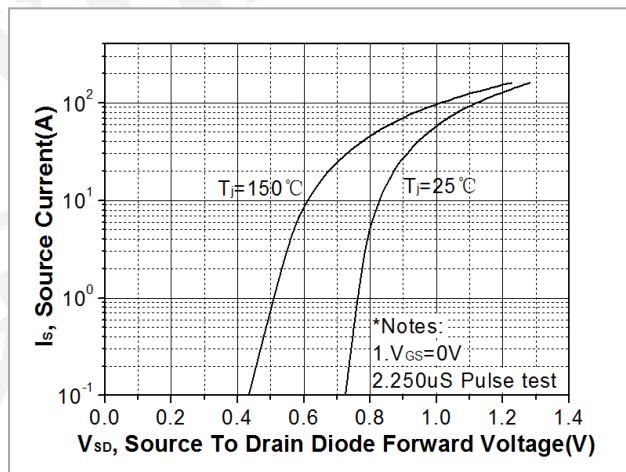
**Fig. 2. Transfer Characteristics**



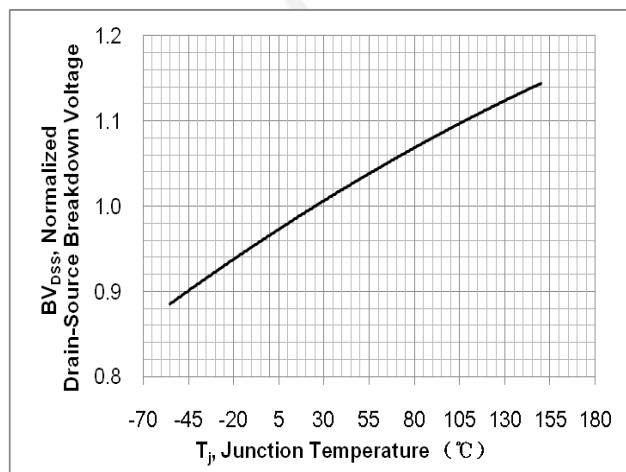
**Fig. 3. On-resistance variation vs. drain current and gate voltage**



**Fig. 4. On-state current vs. diode forward voltage**



**Fig 5. Breakdown voltage variation vs. junction temperature**



**Fig. 6. On-resistance variation vs. junction temperature**

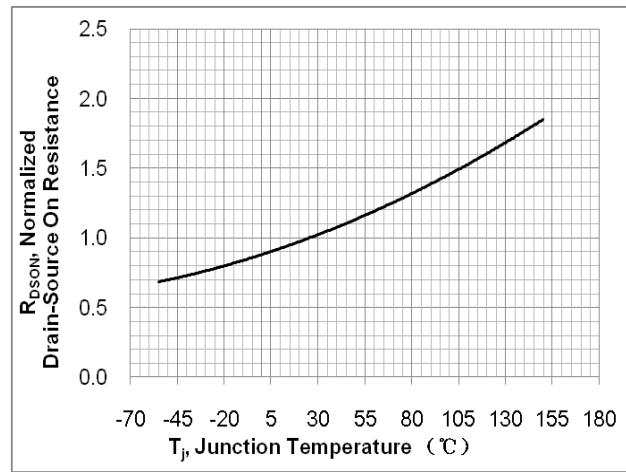


Fig. 7. Gate charge characteristics

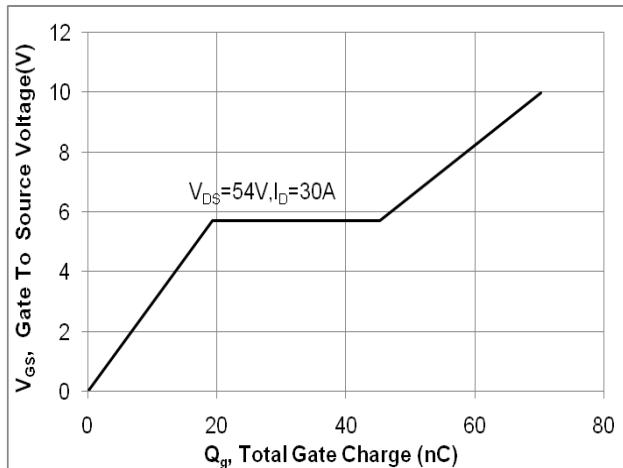


Fig. 8. Capacitance Characteristics

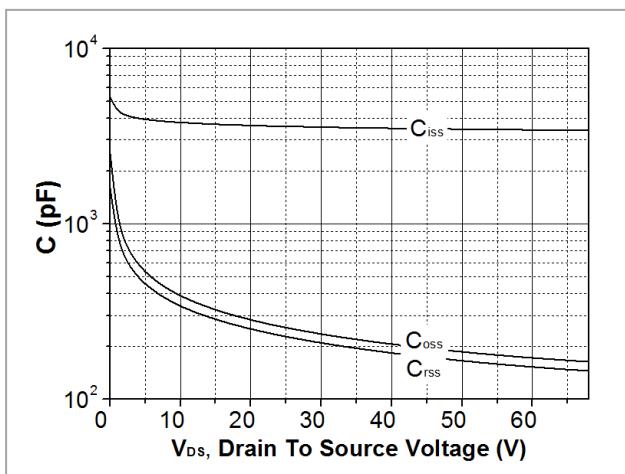


Fig. 9. Maximum safe operating area  
(TO-220&TO-263)

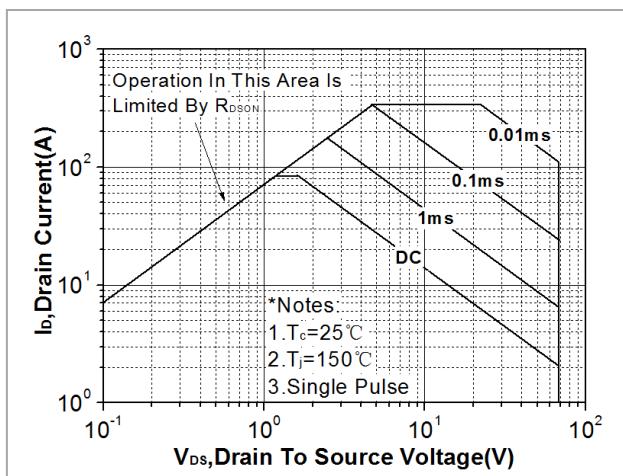


Fig. 10. Maximum drain current vs. case temperature

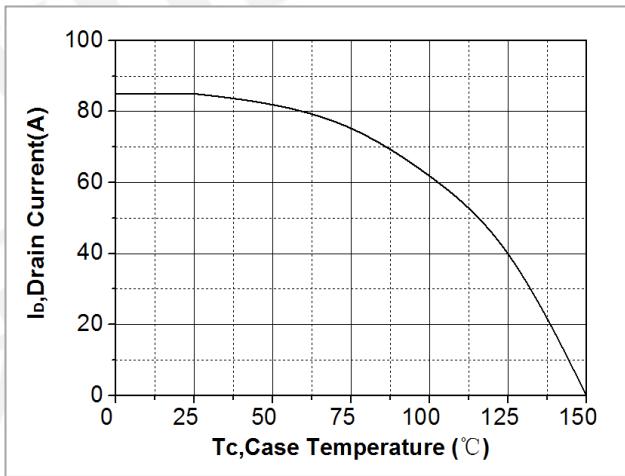


Fig. 11. Transient thermal response curve(TO-220&TO-263)

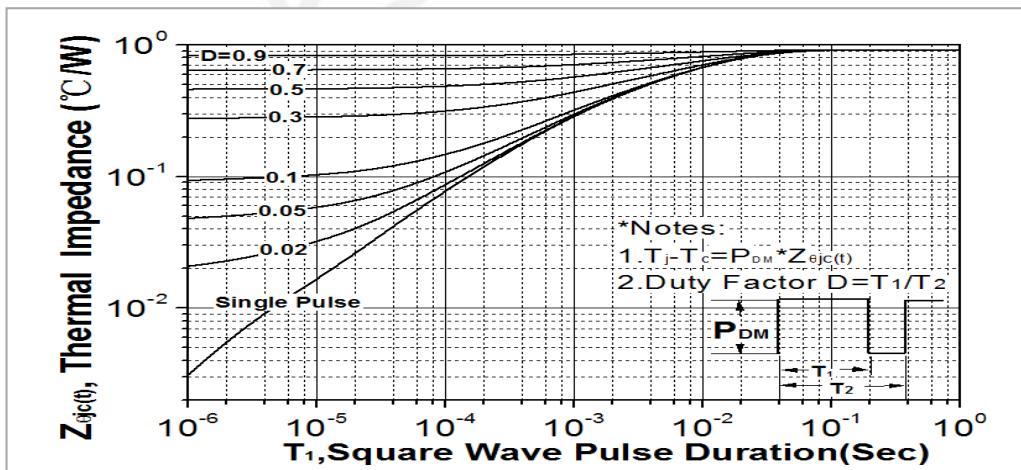


Fig. 12. Gate charge test circuit & waveform

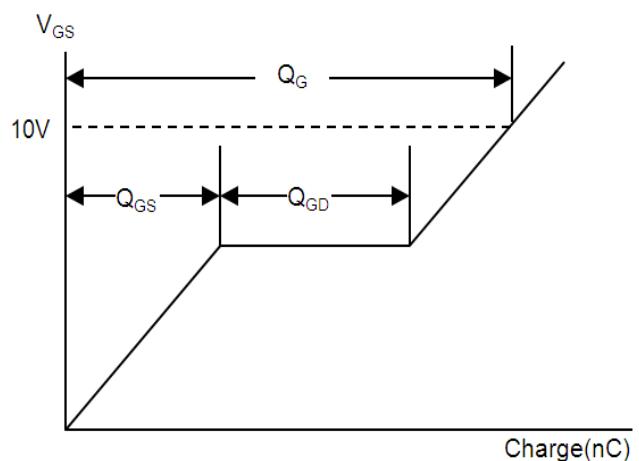
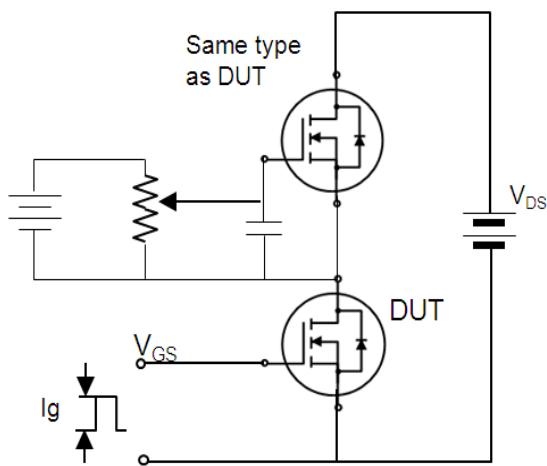


Fig. 13. Switching time test circuit & waveform

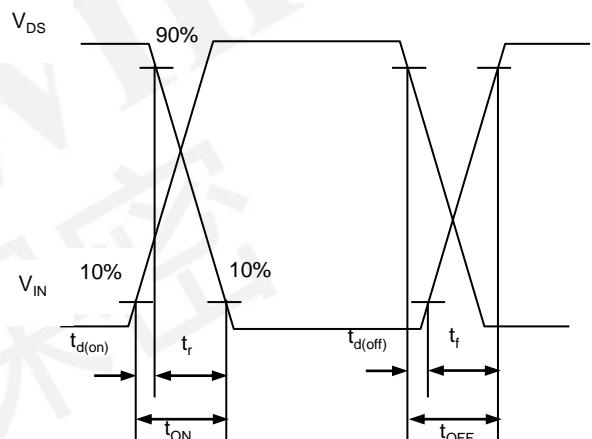
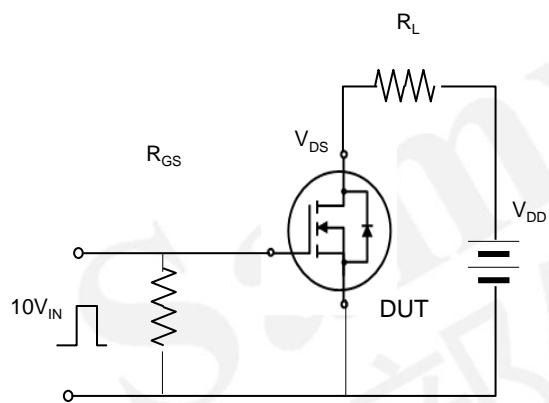


Fig. 14. Unclamped Inductive switching test circuit & waveform

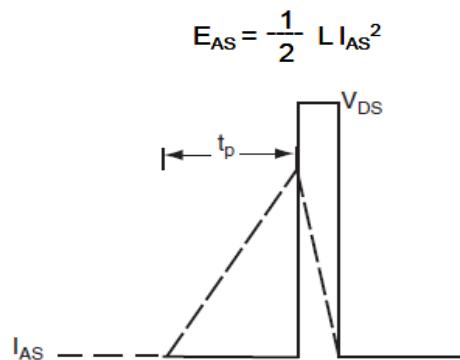
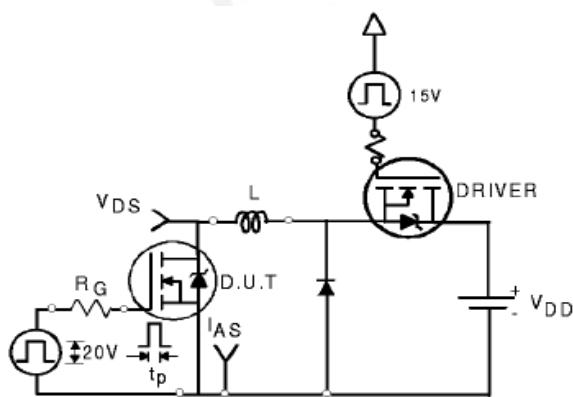
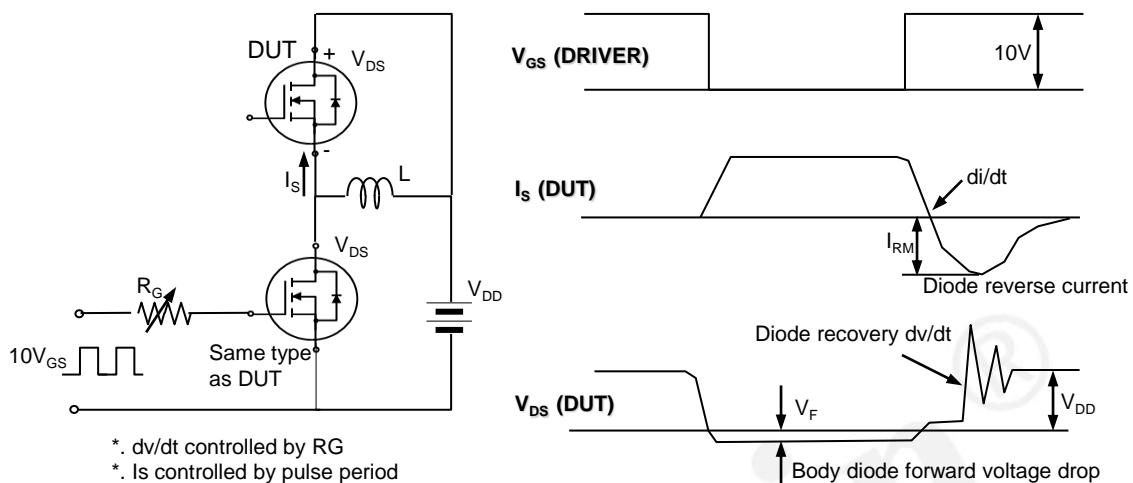


Fig. 15. Peak diode recovery dv/dt test circuit & waveform



### DISCLAIMER

- \* All the data & curve in this document was tested in SEMIPOWER TESTING & APPLICATION CENTER.
- \* This product has passed the PCT, TC, HTRB, HTGB, HAST, PC and Solderdunk reliability testing.
- \* Qualification standards can also be found on the Web site (<http://www.semipower.com.cn>)
- \* Suggestions for improvement are appreciated, Please send your suggestions to [samwin@samwinsemi.com](mailto:samwin@samwinsemi.com)

# X-ON Electronics

Largest Supplier of Electrical and Electronic Components

***Click to view similar products for MOSFET category:***

***Click to view products by Sam&wing manufacturer:***

Other Similar products are found below :

[IRFD120](#) [JANTX2N5237](#) [BUK455-60A/B](#) [MIC4420CM-TR](#) [VN1206L](#) [NDP4060](#) [SI4482DY](#) [IPS70R2K0CEAKMA1](#) [SQD23N06-31L-GE3](#)  
[TK16J60W,S1VQ\(O](#) [2SK2614\(TE16L1,Q\)](#) [DMN1017UCP3-7](#) [DMN1053UCP4-7](#) [SQJ469EP-T1-GE3](#) [NTE2384](#) [DMC2700UDMQ-7](#)  
[DMN2080UCB4-7](#) [DMN61D9UWQ-13](#) [US6M2GTR](#) [DMN31D5UDJ-7](#) [DMP22D4UFO-7B](#) [DMN1006UCA6-7](#) [DMN16M9UCA6-7](#)  
[STF5N65M6](#) [IRF40H233XTMA1](#) [STU5N65M6](#) [DMN6022SSD-13](#) [DMN13M9UCA6-7](#) [DMTH10H4M6SPS-13](#) [DMN2990UFB-7B](#)  
[IPB80P04P405ATMA2](#) [2N7002W-G](#) [MCAC30N06Y-TP](#) [MCQ7328-TP](#) [NTMC083NP10M5L](#) [BXP7N65D](#) [BXP4N65F](#) [AOL1454G](#)  
[WMJ80N60C4](#) [BXP2N20L](#) [BXP2N65D](#) [BXT1150N10J](#) [BXT1700P06M](#) [TSM60NB380CP ROG](#) [RQ7L055BGTCR](#) [DMNH15H110SK3-13](#)  
[SLF10N65ABV2](#) [BSO203SP](#) [BSO211P](#) [IPA60R230P6](#)